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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Active
Number of LABs/CLBs	217080
Number of Logic Elements/Cells	570000
Total RAM Bits	42082304
Number of I/O	588
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FCBGA (40x40)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/10ax057n4f40i3sg">https://www.e-xfl.com/product-detail/intel/10ax057n4f40i3sg</a>



## Intel® Arria® 10 Device Overview

The Intel® Arria® 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

**Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices**

Market	Applications
Wireless	<ul style="list-style-type: none"> <li>• Channel and switch cards in remote radio heads</li> <li>• Mobile backhaul</li> </ul>
Wireline	<ul style="list-style-type: none"> <li>• 40G/100G muxponders and transponders</li> <li>• 100G line cards</li> <li>• Bridging</li> <li>• Aggregation</li> </ul>
Broadcast	<ul style="list-style-type: none"> <li>• Studio switches</li> <li>• Servers and transport</li> <li>• Videoconferencing</li> <li>• Professional audio and video</li> </ul>
Computing and Storage	<ul style="list-style-type: none"> <li>• Flash cache</li> <li>• Cloud computing servers</li> <li>• Server acceleration</li> </ul>
Medical	<ul style="list-style-type: none"> <li>• Diagnostic scanners</li> <li>• Diagnostic imaging</li> </ul>
Military	<ul style="list-style-type: none"> <li>• Missile guidance and control</li> <li>• Radar</li> <li>• Electronic warfare</li> <li>• Secure communications</li> </ul>

### Related Information

#### Intel Arria 10 Device Handbook: Known Issues

Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.



Feature	Description	
Embedded Hard IP blocks	Variable-precision DSP	<ul style="list-style-type: none"><li>• Native support for signal processing precision levels from 18 x 19 to 54 x 54</li><li>• Native support for 27 x 27 multiplier mode</li><li>• 64-bit accumulator and cascade for systolic finite impulse responses (FIRs)</li><li>• Internal coefficient memory banks</li><li>• Preadder/subtractor for improved efficiency</li><li>• Additional pipeline register to increase performance and reduce power</li><li>• Supports floating point arithmetic:<ul style="list-style-type: none"><li>— Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication.</li><li>— Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability.</li><li>— Dynamic accumulator reset control.</li><li>— Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks.</li></ul></li></ul>
	Memory controller	DDR4, DDR3, and DDR3L
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port
	Transceiver I/O	<ul style="list-style-type: none"><li>• 10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC)</li><li>• PCS hard IPs that support:<ul style="list-style-type: none"><li>— 10-Gbps Ethernet (10GbE)</li><li>— PCIe PIPE interface</li><li>— Interlaken</li><li>— Gbps Ethernet (GbE)</li><li>— Common Public Radio Interface (CPRI) with deterministic latency support</li><li>— Gigabit-capable passive optical network (GPON) with fast lock-time support</li></ul></li><li>• 13.5G JESD204b</li><li>• 8B/10B, 64B/66B, 64B/67B encoders and decoders</li><li>• Custom mode support for proprietary protocols</li></ul>
Core clock networks	<ul style="list-style-type: none"><li>• Up to 800 MHz fabric clocking, depending on the application:<ul style="list-style-type: none"><li>— 667 MHz external memory interface clocking with 2,400 Mbps DDR4 interface</li><li>— 800 MHz LVDS interface clocking with 1,600 Mbps LVDS interface</li></ul></li><li>• Global, regional, and peripheral clock networks</li><li>• Clock networks that are not used can be gated to reduce dynamic power</li></ul>	
Phase-locked loops (PLLs)	<ul style="list-style-type: none"><li>• High-resolution fractional synthesis PLLs:<ul style="list-style-type: none"><li>— Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB)</li><li>— Support integer mode and fractional mode</li><li>— Fractional mode support with third-order delta-sigma modulation</li></ul></li><li>• Integer PLLs:<ul style="list-style-type: none"><li>— Adjacent to general purpose I/Os</li><li>— Support external memory and LVDS interfaces</li></ul></li></ul>	
FPGA General-purpose I/Os (GPIOs)	<ul style="list-style-type: none"><li>• 1.6 Gbps LVDS—every pair can be configured as receiver or transmitter</li><li>• On-chip termination (OCT)</li><li>• 1.2 V to 3.0 V single-ended LVTTTL/LVCMOS interfacing</li></ul>	
External Memory Interface	<ul style="list-style-type: none"><li>• Hard memory controller— DDR4, DDR3, and DDR3L support<ul style="list-style-type: none"><li>— DDR4—speeds up to 1,200 MHz/2,400 Mbps</li><li>— DDR3—speeds up to 1,067 MHz/2,133 Mbps</li></ul></li><li>• Soft memory controller—provides support for RLDRAM 3<sup>(2)</sup>, QDR IV<sup>(2)</sup>, and QDR II+</li></ul>	
continued...		



**Table 6. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)**

Resource		Product Line			
		GX 570	GX 660	GX 900	GX 1150
Logic Elements (LE) (K)		570	660	900	1,150
ALM		217,080	251,680	339,620	427,200
Register		868,320	1,006,720	1,358,480	1,708,800
Memory (Kb)	M20K	36,000	42,620	48,460	54,260
	MLAB	5,096	5,788	9,386	12,984
Variable-precision DSP Block		1,523	1,687	1,518	1,518
18 x 19 Multiplier		3,046	3,374	3,036	3,036
PLL	Fractional Synthesis	16	16	32	32
	I/O	16	16	16	16
17.4 Gbps Transceiver		48	48	96	96
GPIO <sup>(3)</sup>		696	696	768	768
LVDS Pair <sup>(4)</sup>		324	324	384	384
PCIe Hard IP Block		2	2	4	4
Hard Memory Controller		16	16	16	16

## Package Plan

**Table 7. Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)			F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 160	48	192	6	48	192	12	48	240	12
GX 220	48	192	6	48	192	12	48	240	12
GX 270	—	—	—	48	192	12	48	312	12
GX 320	—	—	—	48	192	12	48	312	12
GX 480	—	—	—	—	—	—	48	312	12



## Available Options

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





## Maximum Resources

**Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices**

Resource		Product Line	
		GT 900	GT 1150
Logic Elements (LE) (K)		900	1,150
ALM		339,620	427,200
Register		1,358,480	1,708,800
Memory (Kb)	M20K	48,460	54,260
	MLAB	9,386	12,984
Variable-precision DSP Block		1,518	1,518
18 x 19 Multiplier		3,036	3,036
PLL	Fractional Synthesis	32	32
	I/O	16	16
Transceiver	17.4 Gbps	72 <sup>(5)</sup>	72 <sup>(5)</sup>
	25.8 Gbps	6	6
GPIO <sup>(6)</sup>		624	624
LVDS Pair <sup>(7)</sup>		312	312
PCIe Hard IP Block		4	4
Hard Memory Controller		16	16

### Related Information

#### Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

## Package Plan

**Table 11. Package Plan for Intel Arria 10 GT Devices**

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm x 45 mm, 1932-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR
GT 900	—	624	72
GT 1150	—	624	72

<sup>(5)</sup> If all 6 GT channels are in use, 12 of the GX channels are not usable.

<sup>(6)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(7)</sup> Each LVDS I/O pair can be used as differential input or output.



### Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

## Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

### Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

## Available Options

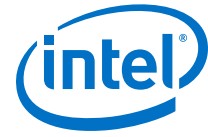
**Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices**



### Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



## I/O Vertical Migration for Intel Arria 10 Devices

**Figure 4. Migration Capability Across Intel Arria 10 Product Lines**

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software **Pin Migration View**.

Variant	Product Line	Package										
		U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
Intel® Arria® 10 GX	GX 160	↑	↑	↑								
	GX 220	↓	↑	↑								
	GX 270		↑	↑	↑	↑						
	GX 320		↓	↑	↑	↑						
	GX 480			↓	↑	↑						
	GX 570				↑	↑	↑	↑				
	GX 660				↑	↓	↑	↑	↑	↑	↑	↑
	GX 900				↑			↑	↑	↑	↑	↑
	GX 1150				↓			↓	↓	↓	↓	↓
	GT 900										↓	↓
	GT 1150										↓	↓
Intel Arria 10 SX	SX 160	↑	↑	↑								
	SX 220	↓	↑	↑								
	SX 270		↑	↑	↑	↑						
	SX 320		↓	↑	↑	↑						
	SX 480			↓	↑	↑						
	SX 570				↑	↑	↑	↑				
	SX 660				↓	↓	↓	↓				

**Note:** To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

## Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



**Figure 5. ALM for Intel Arria 10 Devices**



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

## Variable-Precision DSP Block

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support



## Types of Embedded Memory

The Intel Arria 10 devices contain two types of memory blocks:

- 20 Kb M20K blocks—blocks of dedicated memory resources. The M20K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide and shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Intel Arria 10 devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

## Embedded Memory Capacity in Intel Arria 10 Devices

**Table 18. Embedded Memory Capacity and Distribution in Intel Arria 10 Devices**

Variant	Product Line	M20K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Intel Arria 10 GX	GX 160	440	8,800	1,680	1,050	9,850
	GX 220	587	11,740	2,703	1,690	13,430
	GX 270	750	15,000	3,922	2,452	17,452
	GX 320	891	17,820	4,363	2,727	20,547
	GX 480	1,431	28,620	6,662	4,164	32,784
	GX 570	1,800	36,000	8,153	5,096	41,096
	GX 660	2,131	42,620	9,260	5,788	48,408
	GX 900	2,423	48,460	15,017	9,386	57,846
	GX 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 GT	GT 900	2,423	48,460	15,017	9,386	57,846
	GT 1150	2,713	54,260	20,774	12,984	67,244
Intel Arria 10 SX	SX 160	440	8,800	1,680	1,050	9,850
	SX 220	587	11,740	2,703	1,690	13,430
	SX 270	750	15,000	3,922	2,452	17,452
	SX 320	891	17,820	4,363	2,727	20,547
	SX 480	1,431	28,620	6,662	4,164	32,784
	SX 570	1,800	36,000	8,153	5,096	41,096
	SX 660	2,131	42,620	9,260	5,788	48,408

**Table 20. Memory Standards Supported by the Hard Memory Controller**

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		—	1,200
DDR3 SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	1,067
		—	1,067
DDR3L SDRAM	Half rate	Yes	533
		—	667
	Quarter rate	Yes	933
		—	933
LPDDR3 SDRAM	Half rate	—	533
	Quarter rate	—	800

**Table 21. Memory Standards Supported by the Soft Memory Controller**

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 <sup>(11)</sup>	Quarter rate	1,200
QDR IV SRAM <sup>(11)</sup>	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

**Table 22. Memory Standards Supported by the HPS Hard Memory Controller**

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

<sup>(11)</sup> Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



### **Related Information**

#### [Intel Arria 10 Device Datasheet](#)

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

## **PCIe Gen1, Gen2, and Gen3 Hard IP**

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

### **Related Information**

[PCS Features](#) on page 30

## **Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet**

### **Interlaken Support**

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

### **Related Information**

[PCS Features](#) on page 30

### **10 Gbps Ethernet Support**

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.

Figure 6. Intel Arria 10 Transceiver Block Architecture



## Transceiver Channels

All transceiver channels feature a dedicated Physical Medium Attachment (PMA) and a hardened Physical Coding Sublayer (PCS).

- The PMA provides primary interfacing capabilities to physical channels.
- The PCS typically handles encoding/decoding, word alignment, and other pre-processing functions before transferring data to the FPGA core fabric.

A transceiver channel consists of a PMA and a PCS block. Most transceiver banks have 6 channels. There are some transceiver banks that contain only 3 channels.

A wide variety of bonded and non-bonded data rate configurations is possible using a highly configurable clock distribution network. Up to 80 independent transceiver data rates can be configured.

The following figures are graphical representations of top views of the silicon die, which correspond to reverse views for flip chip packages. Different Intel Arria 10 devices may have different floorplans than the ones shown in the figures.



PCS	Description
Standard PCS	<ul style="list-style-type: none"> <li>Operates at a data rate up to 12 Gbps</li> <li>Supports protocols such as PCI-Express, CPRI 4.2+, GigE, IEEE 1588 in Hard PCS</li> <li>Implements other protocols using Basic/Custom (Standard PCS) transceiver configuration rules.</li> </ul>
Enhanced PCS	<ul style="list-style-type: none"> <li>Performs functions common to most serial data industry standards, such as word alignment, encoding/decoding, and framing, before data is sent or received off-chip through the PMA</li> <li>Handles data transfer to and from the FPGA fabric</li> <li>Handles data transfer internally to and from the PMA</li> <li>Provides frequency compensation</li> <li>Performs channel bonding for multi-channel low skew applications</li> </ul>
PCIe Gen3 PCS	<ul style="list-style-type: none"> <li>Supports the seamless switching of Data and Clock between the Gen1, Gen2, and Gen3 data rates</li> <li>Provides support for PIPE 3.0 features</li> <li>Supports the PIPE interface with the Hard IP enabled, as well as with the Hard IP bypassed</li> </ul>

### Related Information

- [PCIe Gen1, Gen2, and Gen3 Hard IP](#) on page 26
- [Interlaken Support](#) on page 26
- [10 Gbps Ethernet Support](#) on page 26

## PCS Protocol Support

This table lists some of the protocols supported by the Intel Arria 10 transceiver PCS. For more information about the blocks in the transmitter and receiver data paths, refer to the related information.

Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
PCIe Gen3 x1, x2, x4, x8	8.0	Native PHY (PIPE)	Standard PCS and PCIe Gen3 PCS
PCIe Gen2 x1, x2, x4, x8	5.0	Native PHY (PIPE)	Standard PCS
PCIe Gen1 x1, x2, x4, x8	2.5	Native PHY (PIPE)	Standard PCS
1000BASE-X Gigabit Ethernet	1.25	Native PHY	Standard PCS
1000BASE-X Gigabit Ethernet with IEEE 1588v2	1.25	Native PHY	Standard PCS
10GBASE-R	10.3125	Native PHY	Enhanced PCS
10GBASE-R with IEEE 1588v2	10.3125	Native PHY	Enhanced PCS
10GBASE-R with KR FEC	10.3125	Native PHY	Enhanced PCS
10GBASE-KR and 1000BASE-X	10.3125	1G/10GbE and 10GBASE-KR PHY	Standard PCS and Enhanced PCS
Interlaken (CEI-6G/11G)	3.125 to 17.4	Native PHY	Enhanced PCS
SFI-S/SFI-5.2	11.2	Native PHY	Enhanced PCS
10G SDI	10.692	Native PHY	Enhanced PCS
continued...			



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 <sup>(12)</sup> to 2.97	Native PHY	Standard PCS

### Related Information

#### [Intel Arria 10 Transceiver PHY User Guide](#)

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

## SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

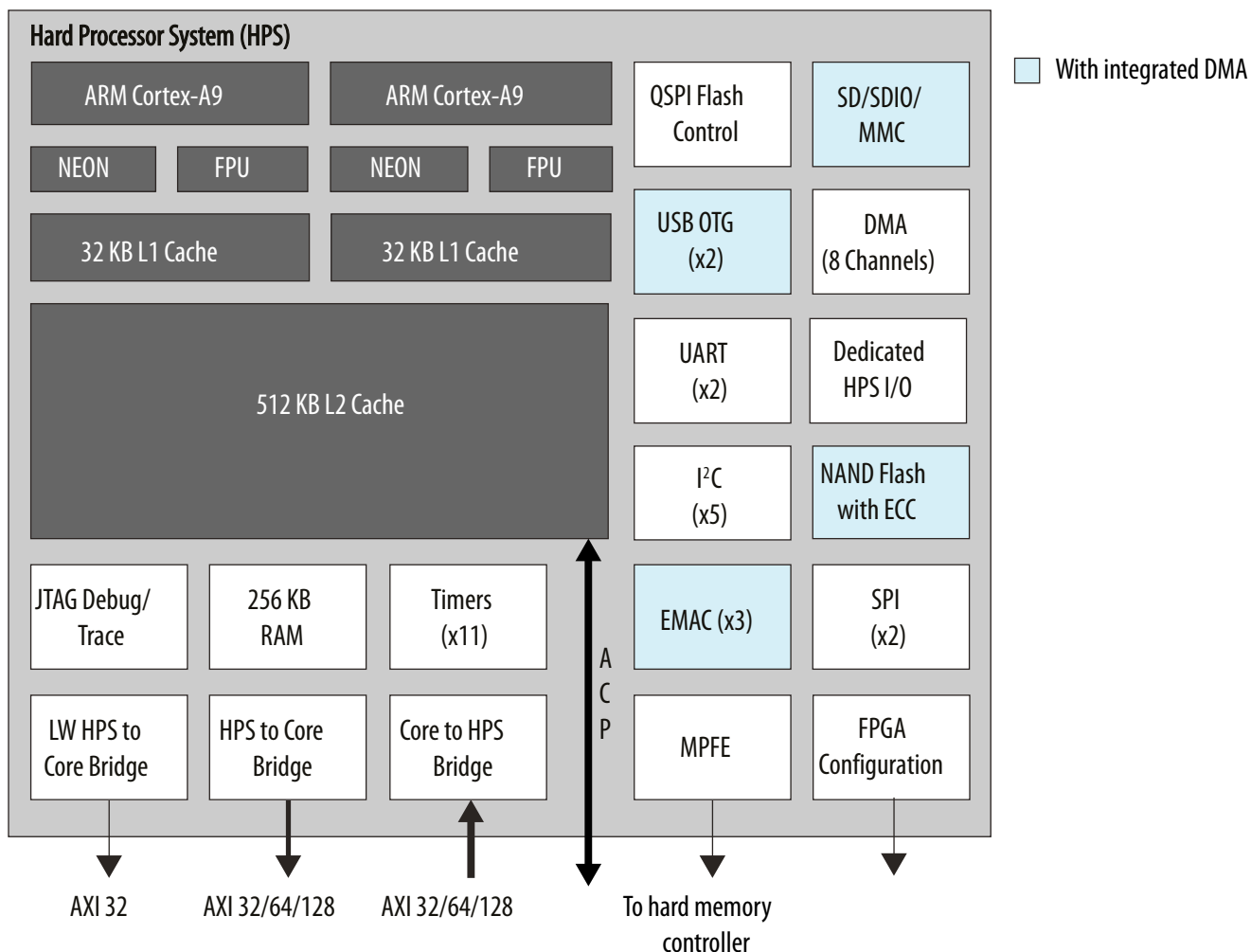
- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

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<sup>(12)</sup> The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.

**Figure 9. HPS Block Diagram**

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



## Key Advantages of 20-nm HPS

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.





**Table 24. Improvements in 20 nm HPS**

This table lists the key improvements of the 20 nm HPS compared to the 28 nm HPS.

Advantages/ Improvements	Description
Increased performance and overdrive capability	While the nominal processor frequency is 1.2 GHz, the 20 nm HPS offers an “overdrive” feature which enables a higher processor operating frequency. This requires a higher supply voltage value that is unique to the HPS and may require a separate regulator.
Increased processor memory bandwidth and DDR4 support	Up to 64-bit DDR4 memory at 2,400 Mbps support is available for the processor. The hard memory controller for the HPS comprises a multi-port front end that manages connections to a single port memory controller. The multi-port front end allows logic core and the HPS to share ports and thereby the available bandwidth of the memory controller.
Flexible I/O sharing	An advanced I/O pin muxing scheme allows improved sharing of I/O between the HPS and the core logic. The following types of I/O are available for SoC: <ul style="list-style-type: none"><li>• 17 dedicated I/Os—physically located inside the HPS block and are not accessible to logic within the core. The 17 dedicated I/Os are used for HPS clock, resets, and interfacing with boot devices, QSPI, and SD/MMC.</li><li>• 48 direct shared I/O—located closest to the HPS block and are ideal for high speed HPS peripherals such as EMAC, USB, and others. There is one bank of 48 I/Os that supports direct sharing where the 48 I/Os can be shared 12 I/Os at a time.</li><li>• Standard (shared) I/O—all standard I/Os can be shared by the HPS peripherals and any logic within the core. For designs where more than 48 I/Os are required to fully use all the peripherals in the HPS, these I/Os can be connected through the core logic.</li></ul>
EMAC core	Three EMAC cores are available in the HPS. The EMAC cores enable an application to support two redundant Ethernet connections; for example, backplane, or two EMAC cores for managing IEEE 1588 time stamp information while allowing a third EMAC core for debug and configuration. All three EMACs can potentially share the same time stamps, simplifying the 1588 time stamping implementation. A new serial time stamp interface allows core logic to access and read the time stamp values. The integrated EMAC controllers can be connected to external Ethernet PHY through the provided MDIO or I <sup>2</sup> C interface.
On-chip memory	The on-chip memory is updated to 256 KB support and can support larger data sets and real time algorithms.
ECC enhancements	Improvements in L2 Cache ECC management allow identification of errors down to the address level. ECC enhancements also enable improved error injection and status reporting via the introduction of new memory mapped access to syndrome and data signals.
HPS to FPGA Interconnect Backbone	Although the HPS and the Logic Core can operate independently, they are tightly coupled via a high-bandwidth system interconnect built from high-performance ARM AMBA AXI bus bridges. IP bus masters in the FPGA fabric have access to HPS bus slaves via the FPGA-to-HPS interconnect. Similarly, HPS bus masters have access to bus slaves in the core fabric via the HPS-to-FPGA bridge. Both bridges are AMBA AXI-3 compliant and support simultaneous read and write transactions. Up to three masters within the core fabric can share the HPS SDRAM controller with the processor. Additionally, the processor can be used to configure the core fabric under program control via a dedicated 32-bit configuration port.
FPGA configuration and HPS booting	The FPGA fabric and HPS in the SoCs are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power. You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility.
Security	New security features have been introduced for anti-tamper management, secure boot, encryption (AES), and authentication (SHA).

## System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

## HPS-FPGA AXI Bridges

The HPS-FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA Avalon/AMBA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to soft peripherals in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS-FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

## HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

The HPS SDRAM controller supports up to 3 masters (command ports), 3x 64-bit read data ports and 3x 64-bit write data ports.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features.



## FPGA Configuration and HPS Booting

The FPGA fabric and HPS in the SoC FPGA must be powered at the same time. You can reduce the clock frequencies or gate the clocks to reduce dynamic power.

Once powered, the FPGA fabric and HPS can be configured independently thus providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- Configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

## Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer system integration tool in the Intel Quartus Prime software.

For software development, the ARM-based SoC FPGA devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Intel SoC FPGAs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux\*, VxWorks\*, and other operating systems are available for the SoC FPGAs. For more information on the operating systems support availability, contact the Intel FPGA sales team.

You can begin device-specific firmware and software development on the Intel SoC FPGA Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

## Dynamic and Partial Reconfiguration

The Intel Arria 10 devices support dynamic and partial reconfiguration. You can use dynamic and partial reconfiguration simultaneously to enable seamless reconfiguration of both the device core and transceivers.

### Dynamic Reconfiguration

You can reconfigure the PMA and PCS blocks while the device continues to operate. This feature allows you to change the data rates, protocol, and analog settings of a channel in a transceiver bank without affecting on-going data transfer in other transceiver banks. This feature is ideal for applications that require dynamic multiprotocol or multirate support.

### Partial Reconfiguration

Using partial reconfiguration, you can reconfigure some parts of the device while keeping the device in operation.



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
  - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
  - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

## Enhanced Configuration and Configuration via Protocol

**Table 25. Configuration Schemes and Features of Intel Arria 10 Devices**

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) <sup>(13)</sup>	Decompression	Design Security <sup>(14)</sup>	Partial Reconfiguration <sup>(15)</sup>	Remote System Update
JTAG	1 bit	33	33	—	—	Yes <sup>(16)</sup>	—
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes <sup>(16)</sup>	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes <sup>(16)</sup>	Parallel Flash Loader (PFL) IP core

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<sup>(13)</sup> Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

<sup>(14)</sup> Encryption and compression cannot be used simultaneously.

<sup>(15)</sup> Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

<sup>(16)</sup> Partial configuration can be performed only when it is configured as internal host.



Date	Version	Changes
December 2015	2015.12.14	<ul style="list-style-type: none"> <li>Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb.</li> <li>Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources.</li> </ul>
November 2015	2015.11.02	<ul style="list-style-type: none"> <li>Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660.</li> <li>Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in <b>Number of Multipliers in Intel Arria 10 Devices</b> table.</li> <li>Updated the available options for Arria 10 GX, GT, and SX.</li> <li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li> </ul>
June 2015	2015.06.15	Corrected label for Intel Arria 10 GT product lines in the vertical migration figure.
May 2015	2015.05.15	Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller.
May 2015	2015.05.04	<ul style="list-style-type: none"> <li>Added support for 13.5G JESD204b in the Summary of Features table.</li> <li>Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic.</li> <li>Added a note to the table, Maximum Resource Counts for Arria 10 GT devices.</li> <li>Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic.</li> </ul>
January 2015	2015.01.23	<ul style="list-style-type: none"> <li>Added floating point arithmetic features in the Summary of Features table.</li> <li>Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb.</li> <li>Updated the table that lists the memory standards supported by Intel Arria 10 devices.</li> <li>Removed support for DDR3U, LPDDR3 SDRAM, RLD RAM 2, and DDR2.</li> <li>Moved RLD RAM 3 support from hard memory controller to soft memory controller. RLD RAM 3 support uses hard PHY with soft memory controller.</li> <li>Added soft memory controller support for QDR IV.</li> <li>Updated the maximum resource count table to include the number of hard memory controllers available in each device variant.</li> <li>Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps.</li> <li>Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz.</li> <li>Added a feature for fractional synthesis PLLs: PLL cascading.</li> <li>Updated the HPS programmable general-purpose I/Os from 54 to 62.</li> </ul>
September 2014	2014.09.30	<ul style="list-style-type: none"> <li>Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX.</li> <li>Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660.</li> <li>Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150.</li> </ul>
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